/ Revised record

/ Descriptions

SOD-123

Silicon Diode in a SOD-123 Plastic Package.

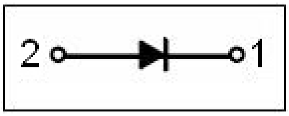
/ Features

Low forward voltage drop, Guard ring construction for transient Protection. High Conductance, Also Available in Lead Free Version. HF Product.

/ Applications

Silicon diode.

/ Equivalent Circuit



/ Pinning

1

2

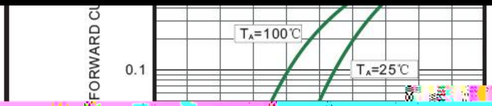
PIN1:Cathode PIN2:Anode

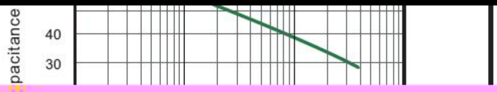
/ h_{FE} Classifications & Marking

Model	B0520W	B0530W	B0540W
Marking	HSD	HSE	HSF

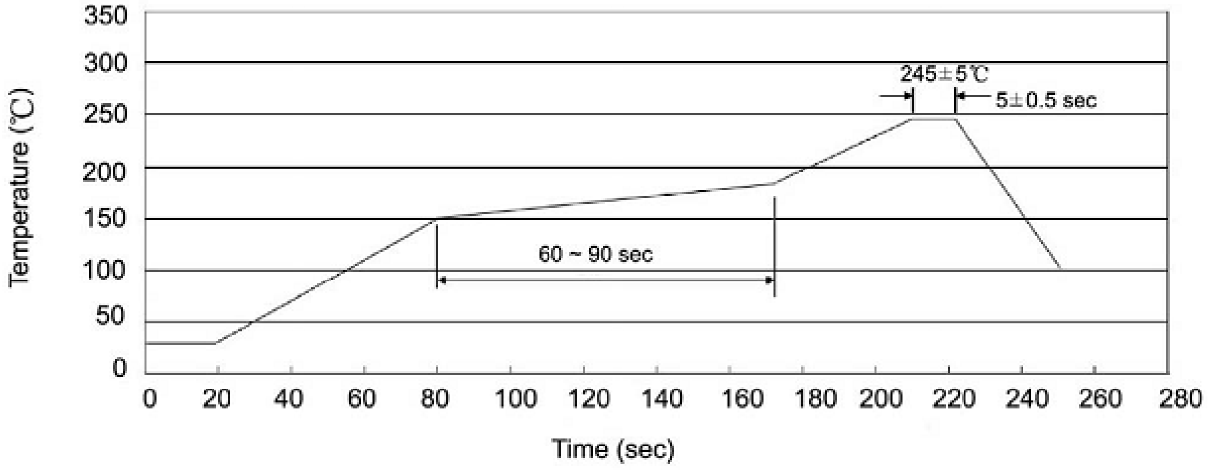
参数 Parameter	符号 Symbol	数值 Rating			单位 Unit
		B0520W	B0530W	B0540W	
Peak Repetitive Reverse Voltage	V_{RRM}	20	30	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	V
Maximum DC Blocking Voltage	V_{DC}	20	30	40	V
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	25			A
Maximum Average Forward Current at Ta=25℃	I_O	0.5			A
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	200			℃/W
Junction temperature	T_j	-55 ~ +125			℃

/ Electrical Characteristic Curve





( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：	Note:
1、预热温度 150～180℃，时间 60～90sec;	1.Preheating:105~180℃, Time:60~90sec.
2、峰值温度 245±5℃，时间持续为 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3、焊接制程冷却速度为 2～10℃/sec.	3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOD-123	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

/ Notices